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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Gilroy J. Vandentop et al.	
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U.S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<u>BV</u>	5,321,583	06/14/1994	McMahon, J.F.	361	770	12/02/92
<u>BV</u>	5,923,083	07/13/1999	Autry, T., et al.	257	688	03/01/97
<u>BV</u>	6,097,609	08/01/2000	Kabadi, A.N.	361	760	12/30/98
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FOREIGN PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes No
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OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

**Examiner Initial	
<u>BV</u>	Ma, L., et al., "Compliant Cantilevered Spring Interconnects for Flip-Chip Packaging", <u>2001 Electronic Components and Technology Conference</u> , 6 pages, (May 2001)
<u>BV</u>	Ma, L., et al., "Novel Nanospring Interconnects for High-Density Applications", <u>2001 International Symposium on Advanced Packaging Materials</u> , 372-378, (March 2001)
<u>BV</u>	Naeemi, A., et al., "Sea of Leads: A Disruptive Paradigm for a System-on-a-Chip (SoC)", <u>ISSCC 2001/Session 17/TP: 3D Technologies and Measurement Techniques/17.7</u> , 280-281, (Feb. 2001)
<u>BV</u>	Reed, H.A., et al., "Compliant Wafer Level Package (CWL) With Embedded Air-gaps for Sea of Leads (SoL) Interconnections", <u>2001 IEEE</u> , 151-153, (June 2001)

Examiner <u>John B. Vignola</u>	Date Considered <u>April 02, 2003</u>
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*Substitute Disclosure Statement Form (PFO-1449)

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